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SO phonon scattering in high-k dielectrics: the role of phonon-plasmon coupling.

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Special request from Anantram: vortices!!



Quantum vortices in nanowire



Sharply defined energy: effect of e.g LER opening a channel: Vortex formation



Density evolution higher energy





Transmission Maximum

2 saddles



Outline

Motivation

- Background: dynamic screening
- Simple LO-phonon plasmon coupling
- Lindhard-Mermin theory
- Coulomb Drag
- Recent experimental studies
- Complex coupling: ideal high k gate stacks
- Complex coupling: non-ideal gate stacks: windowed structure
- Work in progress

Conclusions

Motivation



It has been pointed out [1] that a severe mobility degradation ensues because of the strong coupling of carriers in the channel to surface SO phonons in the vicinity of the dielectric interface.

Recently, we have shown [2] that for ideal interfaces and homogeneous dielectrics it might be possible to offset the mobility degradation by a mobility enhancement that derives from using a strained silicon channel.



Unfortunately, the electron-phonon-plasmon scattering in such structures is a complex process that **involves the entire gate stack** through the coupling of plasmons in the gate and substrate to the phonon modes.

It is not known to what extent the electron-phonon-plasmon scattering strength is **modulated by the interface roughness** at the gate-dielectric interface and indeed, the dielectric/interfacial layer-semiconductor interface.

In addition there is evidence that many of the high κ gate stacks display significant phase separation that will distort our assessment of the spatial dependence of the scattering rates.

Finally, the understanding of the coupling problem requires an evaluation of the effects of the variation of the carrier velocity dispersion (basically electron temperature) between source and drain that acts to modulate the Landau damping of the coupled system.



Metal or poly Si

Interfacial layer SiOx

Si channel

Entire gate stack treated as an electrically interacting dynamical system

1. Naive theory: optical phonons in polar material

Lattice permittivity $\varepsilon_L = \varepsilon_{\infty} \frac{\omega^2 - \omega_L^2}{\omega^2 - \omega_T^2}$

Lyddane-Sachs-Teller

$$\omega_L^2 = \frac{\varepsilon_S}{\varepsilon_\infty} \omega_T^2$$

Longitudinal
$$\omega_L = 30 \quad (meV)$$
Transverse $\omega_T = 27.3 \quad (meV)$

SiO2	A1203	HfO2

TO mode energies

55.6	48.18	12.4
138.1	71.4	48.35

LO mode energies

62.57	56.47	22.2
153.3	120.5	56.5

Units meV

Low energies

Easily excited

Absorption as well

As emission

2. Basic theory: plasmons

Plasma frequency

$$\omega_P^2 = \frac{e^2 n_0}{\varepsilon_\infty m^*}$$

$$\omega_{q}^{2} = \frac{q^{2} \langle v^{2} \rangle}{3\varepsilon_{\infty}/\varepsilon_{0}} = \frac{q^{2}k_{B}T_{e}}{m^{*}\varepsilon_{\infty}/\varepsilon_{0}}$$

Electron Permittivity

$$\varepsilon_e[q,\omega] = \varepsilon_0 - \varepsilon_\infty \frac{\omega_P^2 + \omega_q^2}{\omega(\omega - i\gamma)}$$

Pure plasmon

$$\omega^{2} = \left(\frac{\varepsilon_{\infty}}{\varepsilon_{0}}\right) (\omega_{P}^{2} + \omega_{q}^{2})$$

3. Basic theory: plasmons -lifetime

Plasma frequency

$$\omega_P^2 = \frac{e^2 n_0}{\varepsilon_\infty m^*}$$

Damping (electron scattering on impurities Phonons)

$$\gamma = \frac{1}{\tau} = \gamma[q]$$

 $\omega \tau > 1 \Rightarrow$ well – defined plasma modes

OK for RPA see later

Total permittivity $\varepsilon_T = \varepsilon_L + \varepsilon_e - \varepsilon_0$

For LO modes: $\varepsilon_T = 0$ thus for $\gamma = 0$

$$\omega^4 - \omega^2(\omega_L^2 + \omega_P^2 + \omega_q^2) + \omega_T^2(\omega_P^2 + \omega_q^2) = 0$$

5. Basic theory: coupled modes long wave limit q = 0



6. Basic theory: phonon content, charge factor in long wave limit q = 0



7. Basic theory: effective coupling constant q = 0 long wavelength



Strong anti-screening

8. Basic theory: single particle excitation regime



9. Advanced theory: Lindhard function

$$\varepsilon_{e}(q,\omega) = \varepsilon_{0} - \frac{e^{2}}{q^{2}\Omega} \sum_{\mathbf{k}} \frac{f(\varepsilon_{\mathbf{k}+\mathbf{q}}) - f(\varepsilon_{\mathbf{k}})}{\varepsilon_{\mathbf{k}+\mathbf{q}} - \varepsilon_{\mathbf{k}} - \hbar\omega - i\Gamma}$$

Describes dynamic screening, plasma oscillations,

Landau damping, collisional damping*

$$\begin{split} \varepsilon_{e}[q,\omega] &= \varepsilon_{0} + (\frac{e^{2}}{q^{2}\Omega}) \sum_{\mathbf{k}} f(E_{k}) \times \\ &\left\{ \frac{1}{E_{k-q} - E_{k} + \hbar\omega + i\Gamma} + \frac{1}{E_{k+q} - E_{k} - \hbar\omega - i\Gamma} \right\} \end{split}$$

Summary

1.	$\omega_P << \omega_L$	Weak screening	
2.	$\omega_P \leq \omega_L$	Anti-screening	Soft mode emerges
3.	$\omega_P \geq \omega_L$	Screening	
4.	$\omega_P >> \omega_L$	Strong screening	Entirely plasmon type

$$\begin{split} \lambda(\mathbf{k}) &= \int_{-\infty}^{\infty} d(\hbar\omega) \pi^{-1} \{1 + F_{BE}(\omega)\} \\ &\sum_{\mathbf{q}} \{1 - f(\mathbf{k} + \mathbf{q})\} \frac{2\pi}{\hbar} \left| V(\mathbf{q}) \right|^{2} \operatorname{Im} \{-\frac{1}{\varepsilon(q,\omega)}\} \\ &\delta(\varepsilon_{\mathbf{k}+\mathbf{q}} - \varepsilon_{\mathbf{k}} + \hbar\omega) \end{split}$$



$$\mathrm{Im}\{-\frac{1}{\varepsilon(q,\omega)}\} = -\mathrm{Im}\{\frac{1}{\varepsilon_{\infty}} - \frac{\omega_{LO}}{2}(\frac{1}{\varepsilon_{\infty}} - \frac{1}{\varepsilon_{0}})(\frac{1}{\omega_{LO} - \omega + i\eta} + \frac{1}{\omega + \omega_{LO} + i\eta})\}$$

$$= \frac{1}{2}\omega_{LO}\pi(\frac{1}{\varepsilon_{\infty}} - \frac{1}{\varepsilon_{0}})\{\delta(\omega - \omega_{LO}) - \delta(\omega + \omega_{LO})\}$$



Lindhard formula in RPA

$$\varepsilon_{e}(q,\omega) = \varepsilon_{0} - \frac{e^{2}}{q^{2}\Omega} \sum_{\mathbf{k}} \frac{f(\varepsilon_{\mathbf{k}+\mathbf{q}}) - f(\varepsilon_{\mathbf{k}})}{\varepsilon_{\mathbf{k}+\mathbf{q}} - \varepsilon_{\mathbf{k}} - \hbar\omega - i\Gamma}$$

Exact solutions at T=0, gamma->0

q->0

Describes dynamic screening, plasma oscillations,

Landau damping, collisional damping*

Zeros of $\operatorname{Re}[\varepsilon_T(q,\omega)] \Longrightarrow$ dispersion relation for modes

Peaks of $\text{Im}[-1/\varepsilon_T(q,\omega)] \Rightarrow \text{microscopic energy conserving}$ $"\delta - functions"$

Describes dynamic screening, plasma oscillations,

Landau damping, collisional damping*

$$\varepsilon_e(q,\omega) = \varepsilon_0 - \frac{e^2 m^*}{4\pi^{3/2} \hbar q^3} \left(\frac{2m^* k_B T}{\hbar^2}\right) \{Z(A^+) - Z(A^-)\}$$

$$Z(z) = \frac{1}{\sqrt{\pi}} \int_{-\infty}^{\infty} \frac{\exp[-u^2]}{u - z} du$$

Plasma dispersion function

$$A_{\pm} = \left(\frac{2m * k_B T}{\hbar^2}\right)^{-1} \left(\frac{m * \omega}{\hbar q} \pm \frac{q}{2} + i\eta\right)$$

Pade approximant for Plasma dispersion function

Essential to handle Monte Carlo numerics

$$Z(z) = \frac{i\sqrt{\pi} + (\pi - 2)z}{1 - i\sqrt{\pi}z - (\pi - 2)z^2}$$

D. Lowe and J.R. Barker (1985)

Degenerate case now derived

J.R.Barker 2005

Remote scattering:

Impurities in gate interact with electrons in channel

Electrons in gate interact with electrons in Channel. **Coulomb drag**

Enhanced by plasmon interactions in the gate.



Metal or poly Si

High k

Interfacial layer SiOx

Si channel

Momentum transfer between non-equilibrium carriers in channel and equilibrium carriers in gate. Fischetti J.App.Phys. 89 1232 (2001)





Fig. 1. Drag momentum transfer equations. Symbol key, subscripts x = c or g refer to channel or gate respectively: e = electronic charge, $n_x =$ sheet electron concentration, $m_x =$ electron effective mass, $\tau_{xj} =$ relaxation time due to j^{th} scattering process, and $\overline{p_x} =$ mean electron momentum. $F_e =$ driving electric field in channel, $F_g =$ induced field in gate, $\mu_g =$ mobility in gate, and $\mu_{eg} =$ the gate-induced mobility in the channel.

Recent experimental studies

Relevance of Remote Scattering in Gate to Channel Mobility of thin-oxide CMOS devices.

Paul M. Solomon and Min Yang

IEDM 2004

IBM Semiconductor Research and Development Center: Research Division, T.J. Watson research Center, Yorktown Heights, NY 10598, E-mail: solomono@us.ibm.com Phone:(914) 945-2841 Fax: (914) 945-2141 Abstract

Coulomb drag between electrons in the channel, and electrons in the gate was measured for the first time on silicon MOSFETs having different gate oxide thicknesses and polysilicon doping levels. These measurements were augmented by mobility measurements in both the channel and the gate. The drag results showed current transfer ratios between channel and gate of $\sim 2 \times 10^{-4}$, and not to be a strong function of oxide thickness in the 1.9-2.8 nm range. The derived transfer mobility between channel and gate is $\sim 1.5 \times 10^4 \text{ cm}^2/\text{V-s}$, too large to significantly affect channel current. We show also that neither drag nor remote impurity scattering can account for mobility degradation observed on our thinner oxide samples.



Fig. 5. Drag voltage measured on gate (\bullet) and channel (o) with signal applied to channel and gate. Full scale = 0.1 and 5µV respectively



Fig. 10. Channel/gate current transfer ratio vs. oxide thickness for implants D (solid) and C (dashed) and for different channel electron concentrations as indicated.

Implications

The strong plasmon enhanced drag predicted by Fischetti. [1] is not seen. Our values for current transfer ratio and gate mobility yield a transfer mobility, $\mu_{cg}=A_I/\mu_g$, of ~15,000 cm²/ V-s for our 1.9nm oxide, which would not cause significant mobility degradation in the FET channel. This is most likely a consequence of the very strong scattering in the polysilicon, which prevents plasmons from forming. This, coupled with the weak thickness dependence (see Fig. 10), is good news implying that gate-induced drag will not limit mobility for even thinner oxides. Drag may be still important, as pointed out by Fischetti, between the channel and S/D regions.

The IBM data may be interpreted as due to strong scattering in the poly-silicon gate leading to a **collisional broadening of the Lindhard function**. If τ_C is the collision rate the simplest extension to Lindhard formula that conserves particle number is:

$$\varepsilon_e[q,\omega] \to \varepsilon_0 + \frac{(1+i/\omega\tau_c)(\varepsilon_e[q,\omega] - \varepsilon_0)}{1+(i/\omega\tau_c)\frac{(\varepsilon_e[q,\omega] - \varepsilon_0)}{(\varepsilon_e[q,0] - \varepsilon_0)}}$$

Strong collisional broadening

c.f Mermin (1970)

$$\omega \tau_c \ll 1 \qquad \varepsilon_e[q,\omega] \to \varepsilon_e[q,0]$$

single particle excitation regime



Complex coupling: ideal high k gate stacks



Plasmons in gate and substrate couple to interface phonons

and dynamic screening of remote impurity/electron/phonon scattering

Basic approach established by

Kim, Das and Senturia Phys.Rev B 18 6890 (1978)Fischetti J.App.Phys. 89 1205 (2001)Fischetti and Laux, J.App. Phys. 89 1232 (2001)Fischetti, Neumayer, Cartier, J.App.Phys. 90 4587 (2001)

Complex coupling: ideal high k gate stacks

Electrostatic potential

$$\varphi(\mathbf{R}, z, t) = \sum_{\mathbf{Q}} \varphi_{Q\omega}(z) \exp[i(\mathbf{Q}\cdot\mathbf{r} + \omega t)]$$

$$\frac{\partial^2 \varphi}{\partial z^2} - Q^2 \varphi = 0$$



2 BoundaryConditions at each interface introduces dielectric functions

Set of sim. Eqns

Vanishing determinant For solution => Dispersion relation $a_0 \exp[Q(z-t_0)]$

$$a_1 \exp[Q(z - t_0)] + b_1 \exp[-Q(z - t_0)]$$

$$a_2 \exp[Q(z - t_0)] + b_2 \exp[-Q(z - t_0)]$$

$$b_n \exp[-Q(z-t_0)]$$

Simple matching: transfer matrix



Dispersion relation

Example: Gate-dielectric-silicon

$$\varepsilon^{2}{}_{hk}(\omega) + \varepsilon_{hk}(\omega) \{\varepsilon_{gate}(\omega) + \varepsilon_{si}(Q,\omega)\} Coth[Q(t_{1} - t_{0})]$$
$$+ \varepsilon_{gate}(\omega)\varepsilon_{si}(Q,\omega) = 0$$

$$\omega = \omega(Q)^{(j)}$$
 $j = 1...6$

Six modes: 2 are weak scattering associated with TO modes

The rest are coupled plasmon-phonon modes

In the Landau damping region the plasma oscillations are damped

Alters scattering strength and energies



Dispersion relation

Example2: Gate-dielectric-interfacial layer-silicon

$$(\varepsilon_{gate} + \varepsilon_{hk})(\varepsilon_{si} + \varepsilon_{oxide})(\varepsilon_{hk} + \varepsilon_{oxide}) + (\varepsilon_{gate} - \varepsilon_{hk})(\varepsilon_{si} + \varepsilon_{oxide})(\varepsilon_{oxide} - \varepsilon_{hk}) \exp[-Q(t_1 - t_0)] - (\varepsilon_{gate} + \varepsilon_{hk})(\varepsilon_{si} - \varepsilon_{oxide})(\varepsilon_{oxide} - \varepsilon_{hk}) \exp[-Q(t_2 - t_0)] = 0$$

$$\omega = \omega(Q)^{(j)} \qquad j = 1...16$$

Sixteen modes: 4 are weak scattering associated with TO modes, 2 in each insulator. The 12 remaining are coupled plasmon-surface phonon modes

In the Landau damping region the plasma oscillations are damped

To treat Landau damping and collisional damping we use Lindhard function

Interfacial layer reduces strength of SO scattering by $\exp[-Qt_{\text{interfacial}}] \sim \exp[-2k_F t_{\text{interfacial}}]$



Low n needs thick layer High n thin layer OK

Complex coupling: non-ideal gate stacks:



Complex coupling: non-ideal gate stacks: windowed structure



Dynamics: effective mass m^* (tensor)Electron temperature $T_e(x,y)$ WMaterial typeIonic Dielectric propertiesLayer thicknessesBare Phonon frequenciesNoCoupling constants

$$m^*(x, y, z) : z \in (t_n, t_{n+1})$$

Windowing involves a filter function c.f DWFT D Wilson-Zak transform

Allows correction and/or smoothing Artefacts from finite cells

Neglects fringing effects at S and D

Overcome by frozen field?

At silicon level :

Dynamically Screened Scattering Rate $\lambda[\mathbf{k}, x, y, z \mid c(x, y, z')]$ Electron temperature $T_e(x, y)$ Plasma frequency depends on n.

Dominant effects:

Modulation of dynamically screened SO interaction and Coulomb drag by interface roughness at each interface.

$$\frac{1}{\tau} \sim \sum_{q} \exp[-q < t >] \cdot \frac{(1 - q\Delta t(\mathbf{r})/2)}{(1 + q\Delta t(\mathbf{r})/2)} \dots$$

Modulation of dynamically screened SO interaction and Coulomb drag by local electron density and electron temperature in channel.

Fractal models of interfaces and phase separation



Seed with generic shapes

Could be used as a growth model



StringFormat [t = '1', 16.96]



StringFormat [t = `1`, 29.68]

StringFormat (t = '1', 10.6)



With same exptal rms height and correlation length

Work in progress

Validation of idealised gate stack theory
-coupled phonons-plasmons, scattering rates

Lindhard formula: fast algorithm for degenerate case

Damped Lindhard model: Landau and Collisional

Port to Monte Carlo 2D/3D

□Port of non-ideal gate stack theory

Surface roughness scattering modulated by plasmon-enhanced SO phonon scattering

 3D Fractal model for mixed phase dielectric-Sematech data?
3D Fractal model for interfaces- build in features from UCL? -generate "typical" structures.

Construction of "typical" local mobility map-> Drift Diffusion?

Conclusions

Extended Fischetti style theory to realistic structures

□Include space dependent electron temperature for degenerate electrons

□Introduce damped Lindhard-Mermin function-new algorithms

Landau damping and collisional damping

□Interface roughness at each interface modulates SO phonon scattering

Spatial dependence of key parameters such as coupled phonon/plasmon frequencies
Using windowed cell method.

□Multi-layer dielectric theory

Fractal models

■ Mobility map to assess devices by DD.

□Future: use secondary self scattering for fast MC computation.



UNIVERSITY of GLASGOW



Biggest vortex in solar system!